

30V P-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

 $V_{(BR)DSS}=-30V$; $R_{DS(ON)}=0.35\Omega$; $I_{D}=-1.0A$

DESCRIPTION

This new generation of high density MOSFETs from Zetex utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.

SOT23

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- · Low gate drive
- SOT23 package

APPLICATIONS

- DC DC Converters
- Power Management Functions
- Disconnect switches
- Motor control

ORDERING INFORMATION

DEVICE	REEL SIZE (inches)	TAPE WIDTH (mm)	QUANTITY PER REEL
ZXM61P03FTA	7	8mm embossed	3000 units
ZXM61P03FTC	13	8mm embossed	10000 units

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DEVICE MARKING

• P03

ABSOLUTE MAXIMUM RATINGS.

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DSS}	-30	V
Gate- Source Voltage	V _{GS}	± 20	V
Continuous Drain Current (V_{GS} =-10V; T_A =25°C)(b) (V_{GS} =-10V; T_A =70°C)(b)	I _D	-1.1 -0.9	А
Pulsed Drain Current (c)	I _{DM}	-4.3	Α
Continuous Source Current (Body Diode)(b)	Is	-0.88	Α
Pulsed Source Current (Body Diode)(c)	I _{SM}	-4.3	А
Power Dissipation at T _A =25°C (a) Linear Derating Factor	P_{D}	625 5	mW mW/°C
Power Dissipation at T _A =25°C (b) Linear Derating Factor	P _D	806 6.4	mW mW/°C
Operating and Storage Temperature Range	T _j :T _{stg}	-55 to +150	°C

THERMAL RESISTANCE

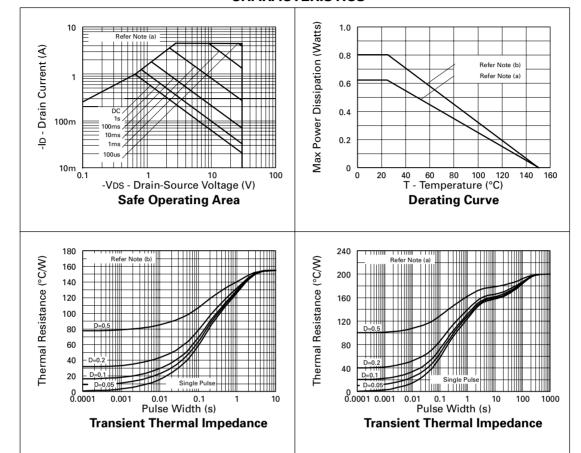
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	200	°C/W
Junction to Ambient (b)	$R_{\theta JA}$	155	°C/W

NOTES

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions
- (b) For a device surface mounted on FR4 PCB measured at t≤5 secs.
- (c) Repetitive rating pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.



CHARACTERISTICS





ELECTRICAL CHARACTERISTICS (at T_{amb} = 25°C unless otherwise stated).

	1					1	
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.	
STATIC							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	-30			V	I_{D} =-250 μ A, V_{GS} =0V	
Zero Gate Voltage Drain Current	I _{DSS}			-1	μА	V _{DS} =-30V, V _{GS} =0V	
Gate-Body Leakage	I _{GSS}			±100	nA	V_{GS} =± 20V, V_{DS} =0V	
Gate-Source Threshold Voltage	$V_{GS(th)}$	-1.0			V	I_{D} =-250 μ A, V_{DS} = V_{GS}	
Static Drain-Source On-State Resistance (1)	R _{DS(on)}			0.35 0.55	$\Omega \Omega$	V _{GS} =-10V, I _D =-0.6A V _{GS} =-4.5V, I _D =-0.3A	
Forward Transconductance (3)	g _{fs}	0.44			s	V _{DS} =-10V,I _D =-0.3A	
DYNAMIC (3)							
Input Capacitance	C _{iss}		140		pF	V _{DS} =-25 V, V _{GS} =0V, f=1MHz	
Output Capacitance	Coss		45		pF		
Reverse Transfer Capacitance	C _{rss}		20		pF	1	
SWITCHING(2) (3)			'				
Turn-On Delay Time	t _{d(on)}		1.9		ns		
Rise Time	t _r		2.9		ns	V _{DD} =-15V, I _D =-0.6A	
Turn-Off Delay Time	t _{d(off)}		8.9		ns	$R_G=6.2\Omega$, $R_D=25\Omega$ (Refer to test circuit)	
Fall Time	t _f		5.0		ns		
Total Gate Charge	Qg			4.8	nC		
Gate-Source Charge	Q _{gs}			0.62	nC	V _{DS} =-24V,V _{GS} =-10V, I _D =-0.6A	
Gate Drain Charge	Q_{gd}			1.3	nC	(Refer to test circuit)	
SOURCE-DRAIN DIODE	1					1	
Diode Forward Voltage (1)	V _{SD}			-0.95	V	T_{j} =25°C, I_{S} =-0.6A, V_{GS} =0V	
Reverse Recovery Time (3)	t _{rr}		14.8		ns	T _j =25°C, I _F =-0.6A, di/dt= 100A/μs	
Reverse Recovery Charge(3)	Q _{rr}		7.7		nC		

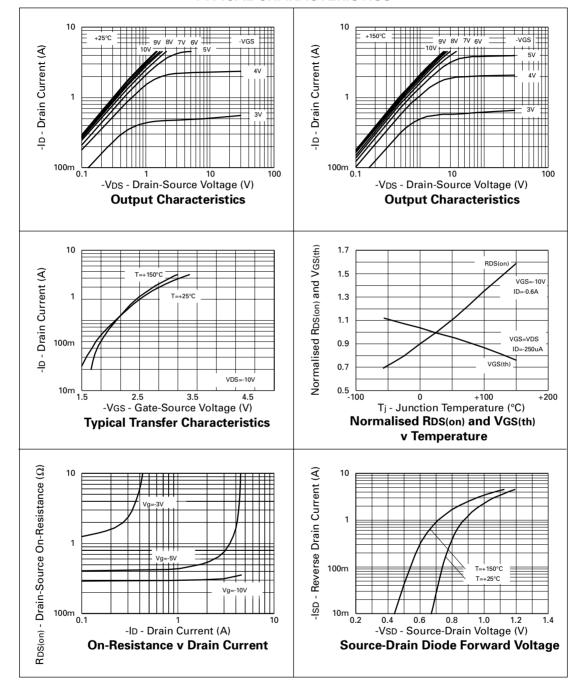
⁽¹⁾ Measured under pulsed conditions. Width=300 μ s. Duty cycle \leq 2% .



⁽²⁾ Switching characteristics are independent of operating junction temperature.

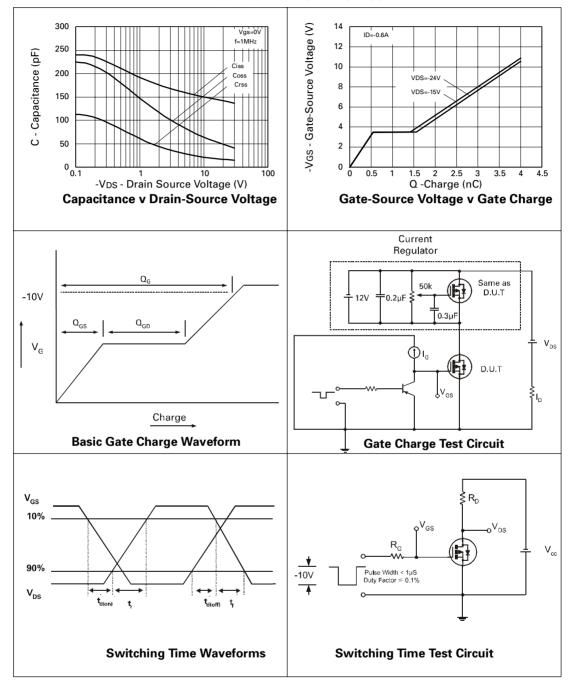
⁽³⁾ For design aid only, not subject to production testing.

TYPICAL CHARACTERISTICS



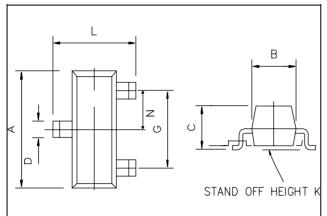


TYPICAL CHARACTERISTICS



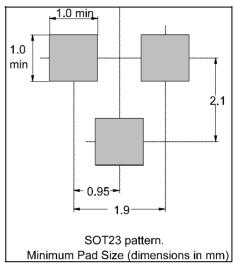


PACKAGE DIMENSIONS



DIM	Millimetres		Inches		
	Min	Max	Min	Max	
Α	2.67	3.05	0.105	0.120	
В	1.20	1.40	0.047	0.055	
С	_	1.10	_	0.043	
D	0.37	0.53	0.0145	0.021	
F	0.085	0.15	0.0033	0.0059	
G	NOM 1.9		NOM 0.075		
K	0.01	0.10	0.0004	0.004	
L	2.10	2.50	0.0825	0.0985	
N	NOM 0.95		NOM 0.037		

PAD LAYOUT DETAILS





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